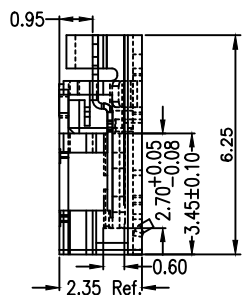
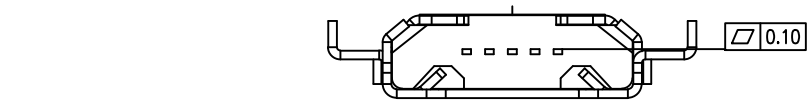
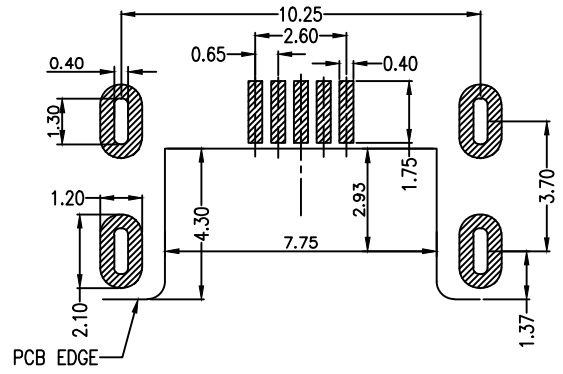
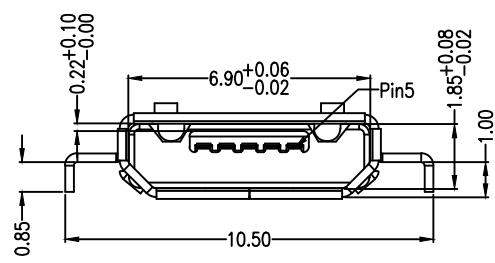
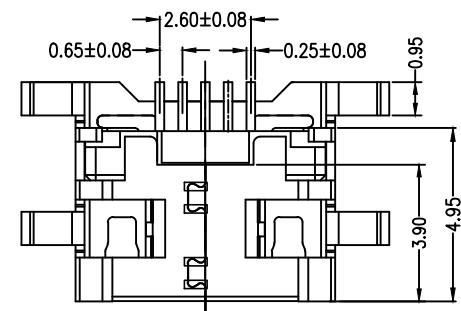
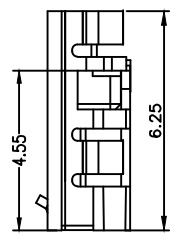
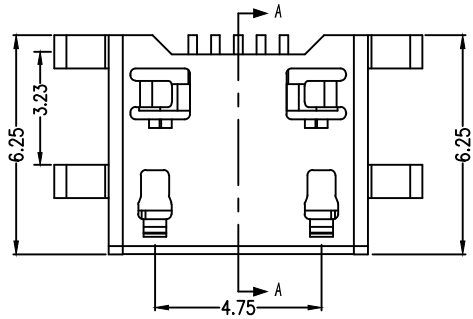


REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE



SEC A-A



Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.15mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:

- 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temperature range: -30°C~80°C

RECOMMENDED PCB LAYOUT

PCB图仅供参考

PART NO: 920-F62A2021S10108		MATERIAL: SEE NOTE		深圳市精拓金子有限公司	
MODEL NO: XX		FINISH: SEE NOTE			
UNIT: MM	SIZE: A4	COLOR: SEE NOTE		TITLE: MICRO/5S B型沉板式1.0四脚插板无边单卡点无孔SMT无接地片片	
TOLERANCE UNSPECIFIED		DR: xiayouhong		DWG NO: A276	
.x	±0.30	CHK:		REV: A	
.xx	±0.20	APP:		SCALE: 5:1	
.xxx	±0.15			DATE: 2012.05.22	
Ang.	±1°				